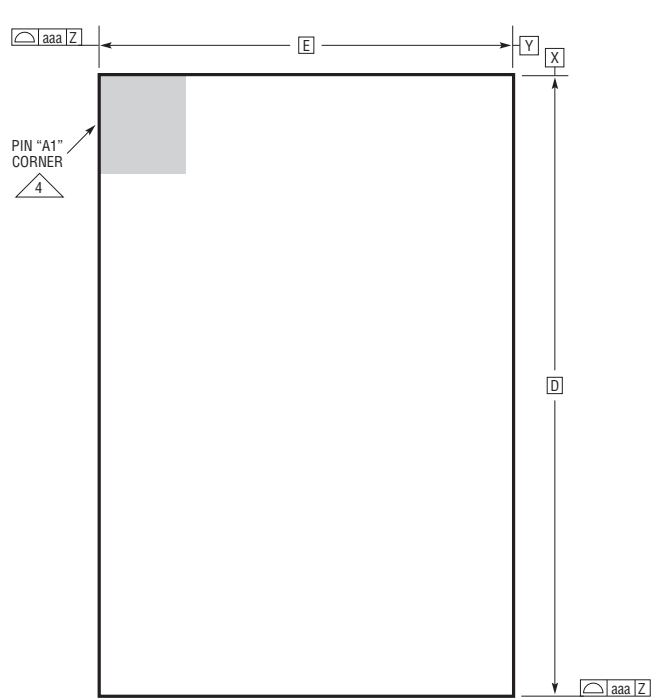
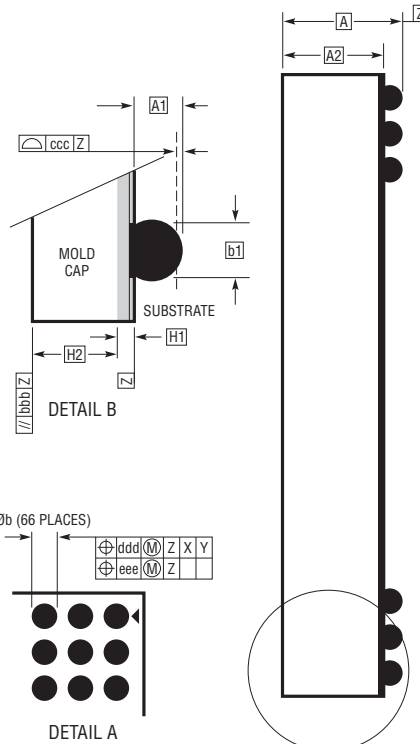


BGA Package
66-Lead (22mm × 15mm × 3.66mm)
 (Reference LTC DWG# 05-08-1509 Rev 0)

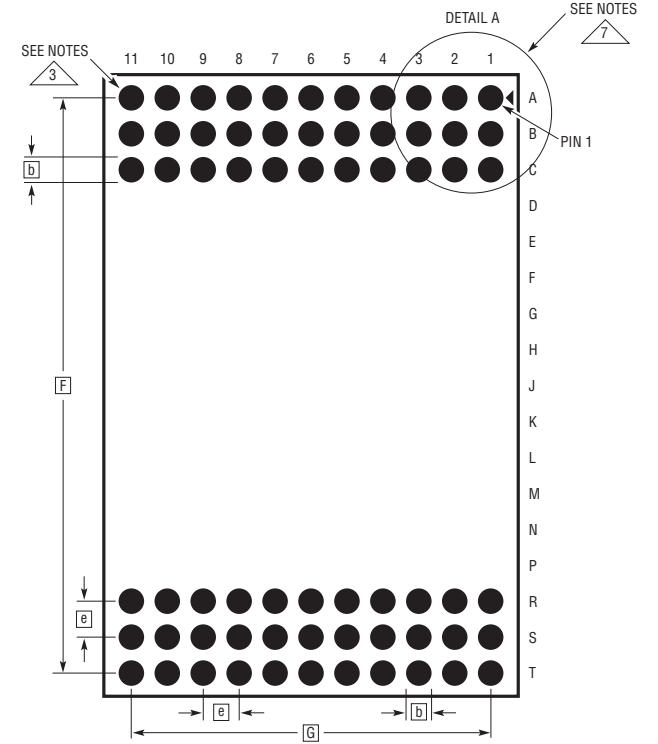


PACKAGE TOP VIEW

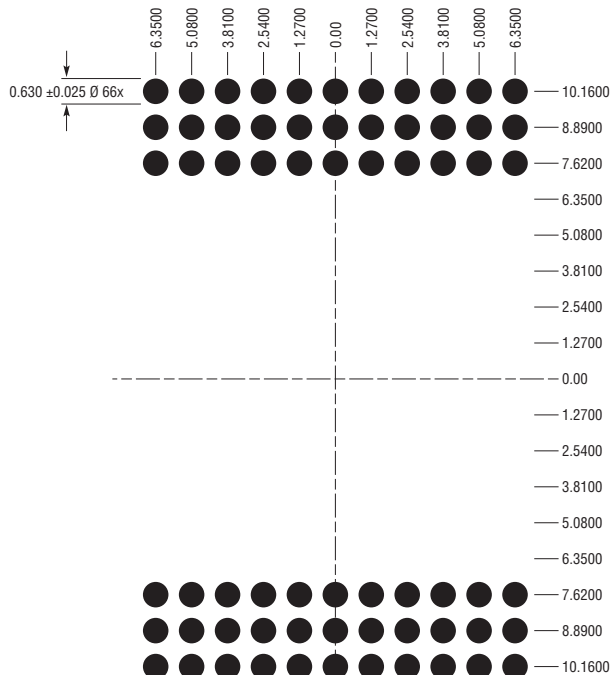


DETAIL A

DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



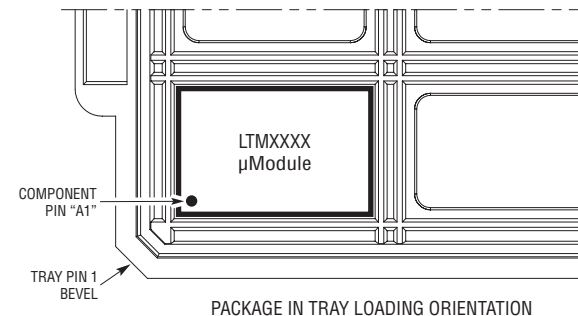
SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.46	3.66	3.86	
A1	0.50	0.60	0.70	BALL HT
A2	2.96	3.06	3.16	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D		22.00		
E		15.00		
e		1.27		
F		20.32		
G		12.70		
H1	0.51	0.56	0.61	SUBSTRATE THK
H2	2.45	2.50	2.55	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 66

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION